

49. The method of forming a data processing card system as recited in claim 48 including the step of providing at least a second chip coupling flexible carrier member having a plurality of electrically conductive chip coupling lead members formed on a first surface thereof for electrically coupling at least a pair of circuit chip devices each to the other.

50. The method of forming a data processing card system as recited in claim 49 where the step of providing said second chip coupling flexible carrier member is followed by the step of sandwiching said second chip coupling flexible carrier member between said second flexible carrier member and a lower surface of said substrate carrier member having a second predetermined lead pattern formed thereon.

51. The method of forming a data processing card system as recited in claim 32 including the step of substantially encapsulating said combined first flexible carrier member and said substrate carrier member.

52. The method of forming a data processing card system as recited in claim 51 where the step of substantially encapsulating includes the step of providing a pair of encapsulating layer members, said combined first flexible carrier member and said substrate carrier member being sandwiched therebetween.

53. The method of forming a data processing card system as recited in claim 52 where the step of providing said pair of encapsulating members includes the step of bonding said encapsulating members to said com-

bined first flexible carrier member and said substrate carrier member.

54. The method of forming a data processing card system as recited in claim 53 where the step of bonding includes the step of heat bonding said pair of encapsulating members to said combined first flexible carrier member and said substrate carrier member.

55. The method of forming a data processing card system as recited in claim 54 where said encapsulating members are substantially planar in contour.

56. The method of forming a data processing card system as recited in claim 55 where said pair of substantially planar encapsulating members are formed of a plastic composition.

57. The method of forming a data processing card system as recited in claim 32 where said flexible carrier member includes a dimensional thickness within the approximating range of 0.005 to 0.01 inches.

58. The method of forming a data processing card system as recited in claim 57 where said flexible carrier member includes a dimensional thickness approximating 0.0075 inches.

59. The method of forming a data processing card system as recited in claim 32 where said chip circuit device includes a dimensional thickness within the approximating range of 0.01 to 0.04 inches.

60. The method of forming a data processing card system as recited in claim 59 where said chip circuit device includes a dimensional thickness approximating 0.02 inches.

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